

MJ N-Channel Enhancement Mode Power MOSFET

Description

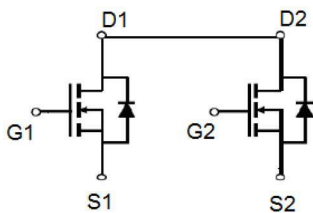
The MJ1608N uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

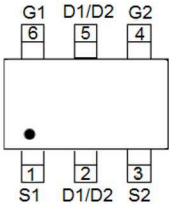
- ◆ $V_{DS}=16V, I_D=8A$
 $R_{DS(ON)} < 16m\Omega @ V_{GS}=2.5V$
 $R_{DS(ON)} < 12m\Omega @ V_{GS}=4.5V$
- ◆ High power and current handling capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

Application

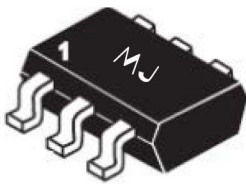
- ◆ Battery protection
- ◆ Load switch
- ◆ Power management



Schematic diagram



Marking and pin assignment



SOT23-6L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
1608N	MJ1608N	SOT23-6L	Ø330mm	12 mm	3000 units

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	16	V
Gate-Source Voltage	V_{GS}	±12	V
Drain Current-Continuous	I_D	8	A
Drain Current-Pulsed ^(Note 1)	I_{DM}	30	A
Maximum Power Dissipation	P_D	1.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance,Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	83.3	°C/W
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Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =16V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{DS} =±12V,V _{GS} =0V	-	-	±100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	0.5	0.7	1.2	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =6A	-	10	12	mΩ
		V _{GS} =2.5V, I _D =5.5A	-	12.9	16	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =6A	-	10	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C _{iss}	V _{DS} =10V,V _{GS} =0V F=1.0MHz	-	1150	-	PF
Output Capacitance	C _{oss}		-	185	-	PF
Reverse Transfer Capacitance	C _{rss}		-	145	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =10V,I _D =6A V _{GS} =4.5V,R _{GEN} =6Ω	-	6	-	nS
Turn-on Rise Time	t _r		-	13	-	nS
Turn-Off Delay Time	t _{d(off)}		-	52	-	nS
Turn-Off Fall Time	t _f		-	16	-	nS
Total Gate Charge	Q _g	V _{DS} =10V,I _D =6A V _{GS} =4.5V	-	15	-	nC
Gate-Source Charge	Q _{gs}		-	0.8	-	nC
Gate-Drain Charge	Q _{gd}		-	3.2	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V _{SD}	V _{GS} =0V,I _S =6A	-	-	1.2	V
Diode Forward Current ^(Note 2)	I _S		-	-	8	A

Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- ④ Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics

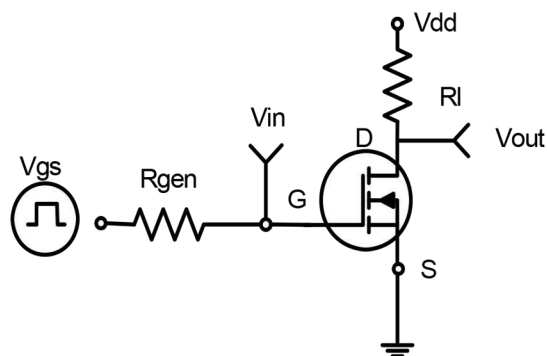


Figure 1 Switching Test Circuit

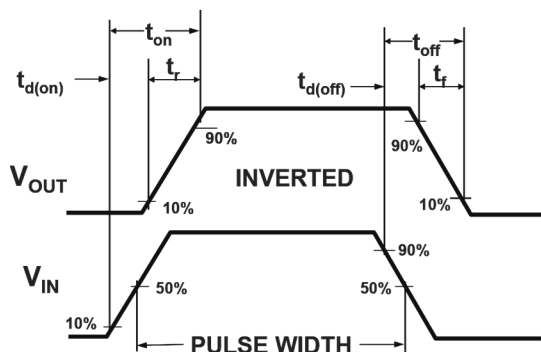


Figure 2 Switching Waveforms

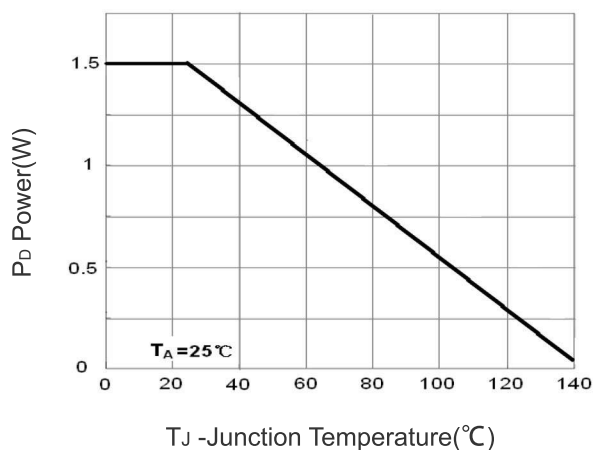


Figure 3 Power Dissipation

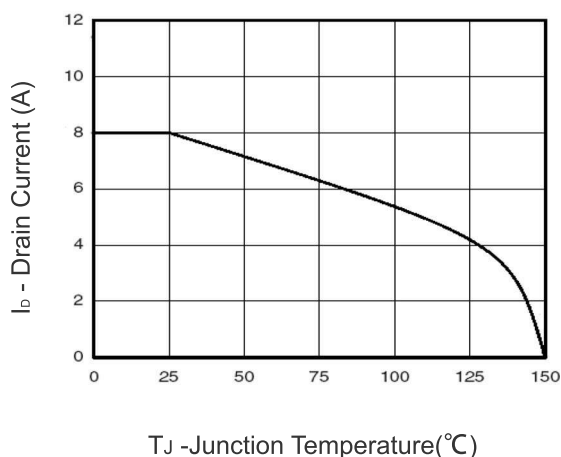


Figure 4 Drain Current

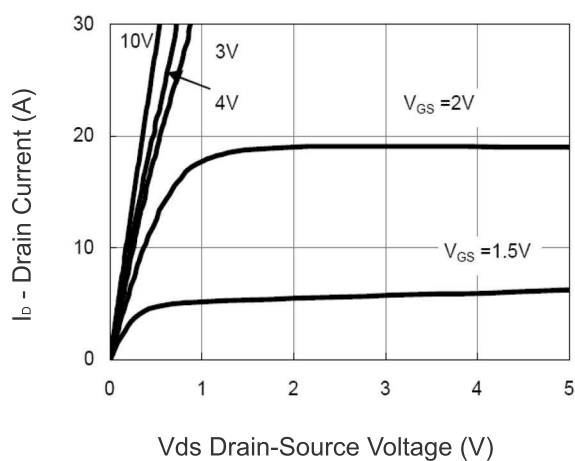


Figure 5 Output Characteristics

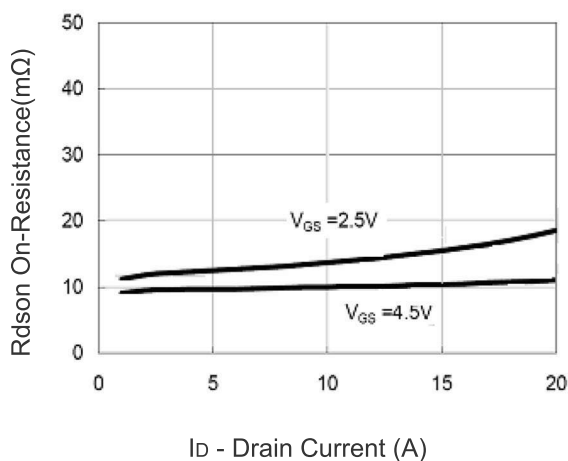


Figure 6 Drain-Source On-Resistance

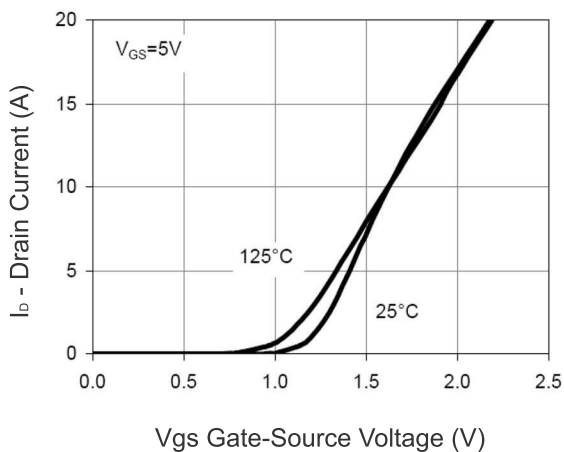


Figure 7 Transfer Characteristics

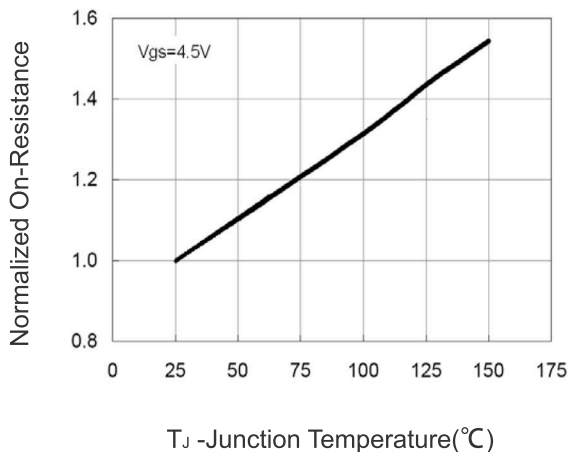


Figure 8 Drain-Source On-Resistance

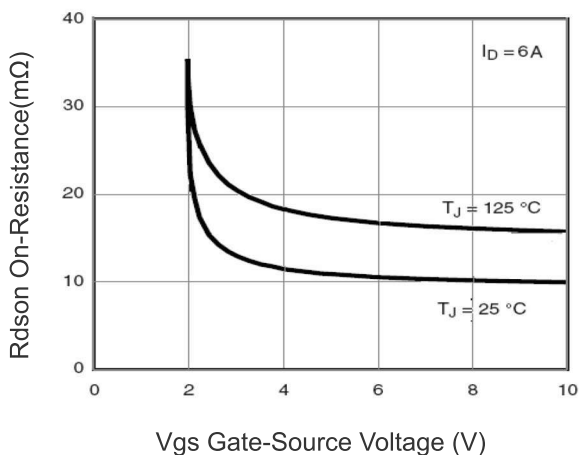


Figure 9 Rdson vs Vgs

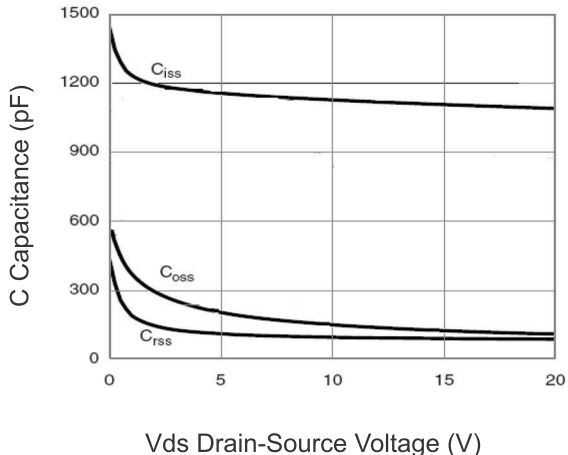


Figure 10 Capacitance vs Vds

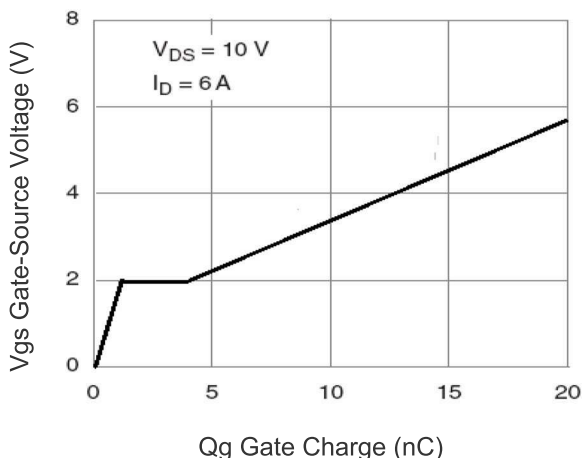


Figure 11 Gate Charge

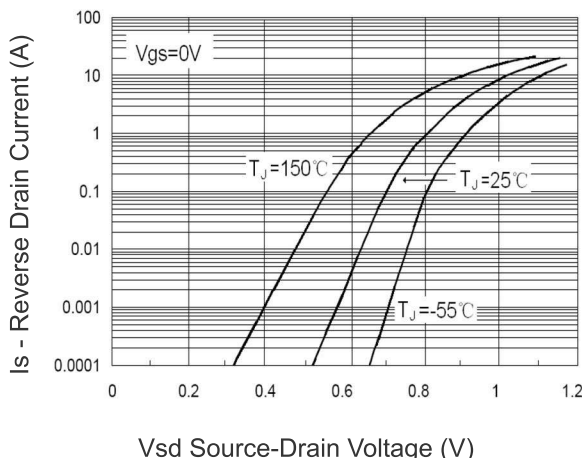
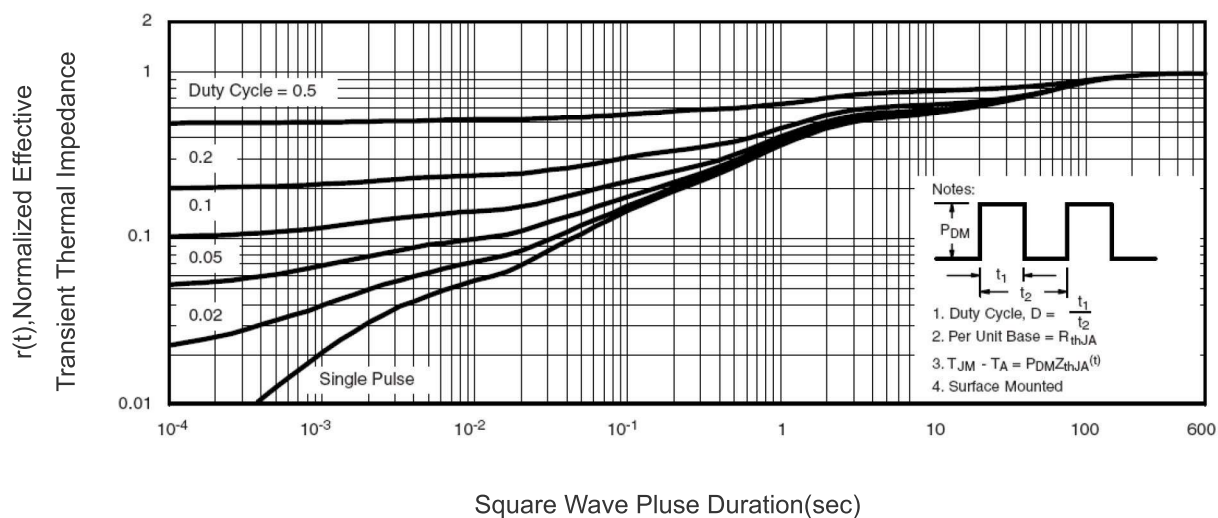
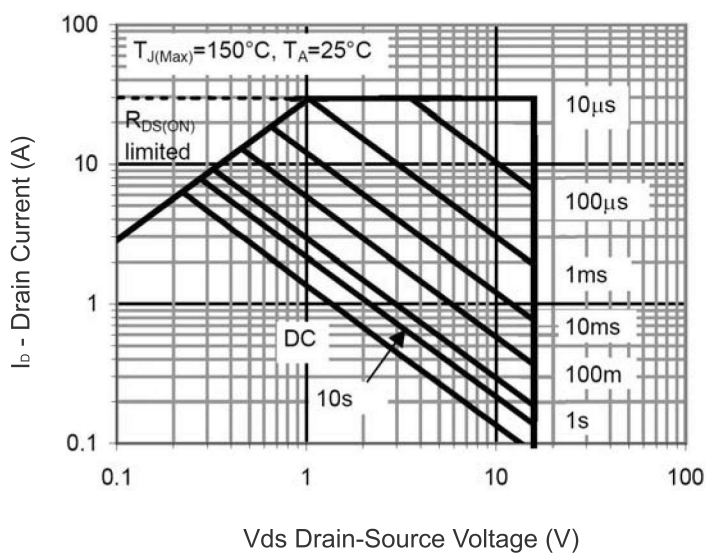


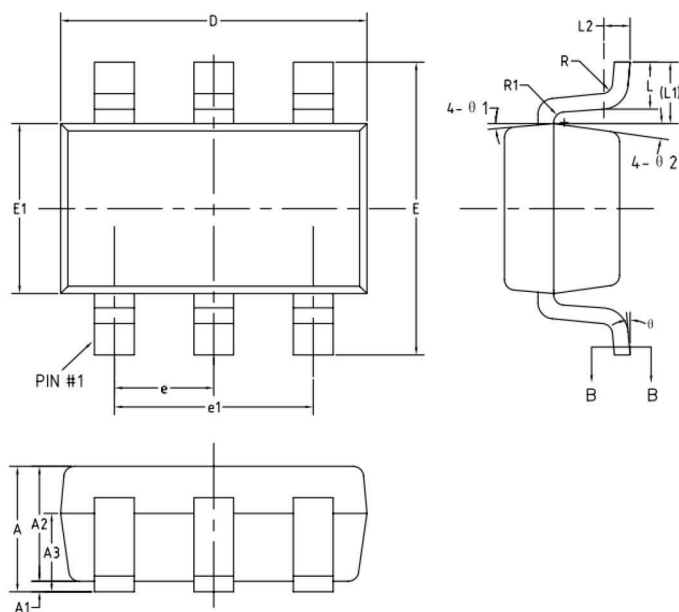
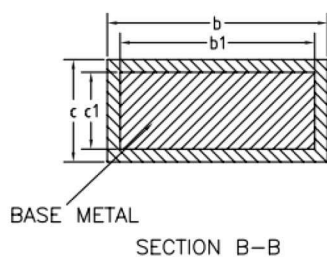
Figure 12 Source- Drain Diode Forward



SOT23-6L Package Information

COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	—	—	1.45
A1	0	—	0.15
A2	0.90	1.10	1.30
A3	0.60	0.65	0.70
b	0.39	—	0.49
b1	0.38	0.40	0.45
c	0.12	—	0.19
c1	0.11	0.13	0.15
D	2.85	2.95	3.05
E	2.60	2.80	3.00
E1	1.55	1.65	1.75
e	0.85	0.95	1.05
e1	1.80	1.90	2.00
L	0.35	0.45	0.60
L1	0.59REF		
L2	0.25BSC		
R	0.05	—	—
R1	0.05	—	0.20
θ	0°	—	8°
θ 1	8°	10°	12°
θ 2	8°	10°	12°



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